

## T-1 3/4 (5mm) BI-LEVEL LED INDICATOR

Part Number: WP1503EB/2ID

High Efficiency Red

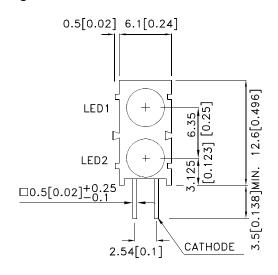
#### **Features**

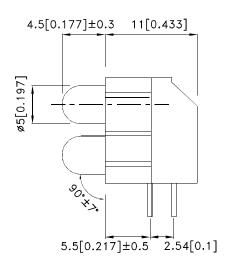
- Pre-trimmed leads for pc board mounting.
- Stackable units.
- Colors can be mixed in a single housing.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

#### Description

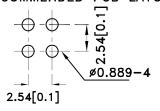
The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

## **Package Dimensions**





#### RECOMMENDED PCB LAYOUT







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
  4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAF2088 **REV NO: V.4A** DATE: FEB/03/2013 PAGE: 1 OF 5 APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Y.Liu ERP: 1102000679

### **Selection Guide**

Part No.	t No. Dice Lens Type		lv (mcd) [2] Lens Type @ 10mA		Viewing Angle [1]
			Min.	Тур.	201/2
MD45005D/0ID	High Efficiency Red (GaAsP/GaP)	Dod Diffused	25	50	60°
WP1503EB/2ID		Red Diffused	*12	*40	

- $1.\,\theta1/2$  is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- Luminous intensity/ luminous Flux: +/-15%.
   Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	IF=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	617		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	IF=20mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	IF=20mA
lr	Reverse Current	High Efficiency Red		10	uA	V <sub>R</sub> = 5V

### Notes:

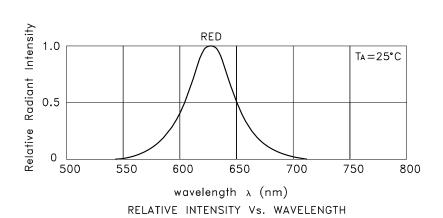
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

### Absolute Maximum Ratings at TA=25°C

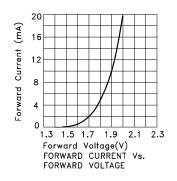
Parameter	High Efficiency Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	160	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

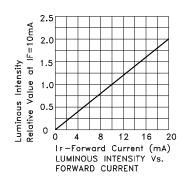
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 2. 2mm below package base.
- 3. 5mm below package base.

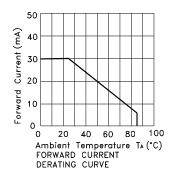
SPEC NO: DSAF2088 **REV NO: V.4A** DATE: FEB/03/2013 PAGE: 2 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Y.Liu ERP: 1102000679

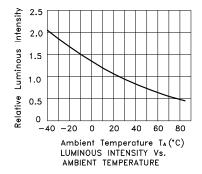


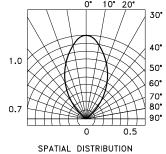
High Efficiency Red WP1503EB/2ID



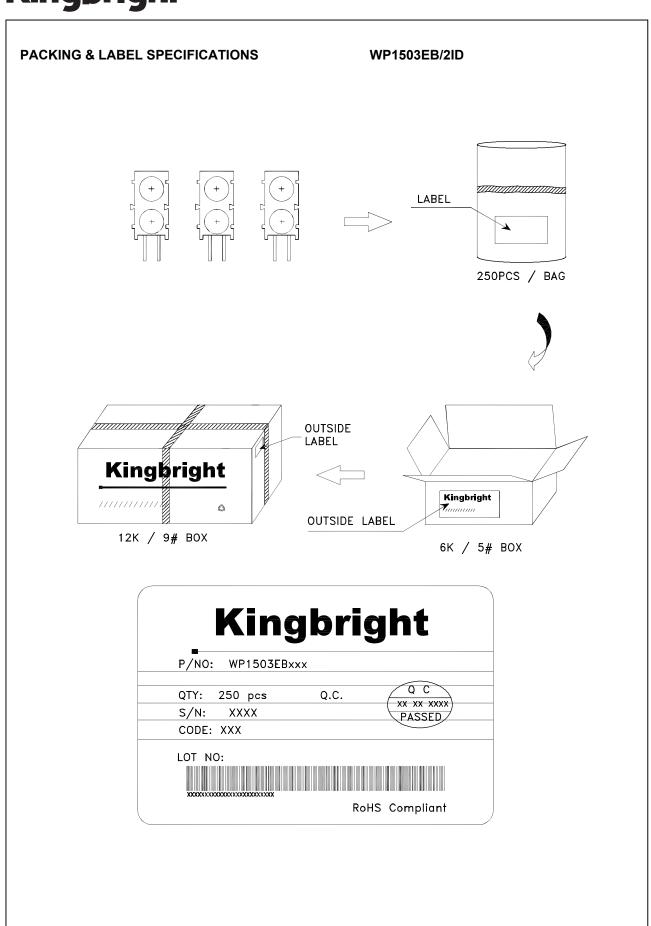








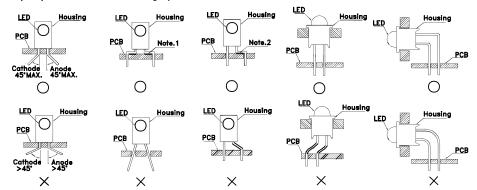
SPEC NO: DSAF2088 REV NO: V.4A DATE: FEB/03/2013 PAGE: 3 OF 5
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Y.Liu ERP: 1102000679



SPEC NO: DSAF2088 APPROVED: WYNEC REV NO: V.4A CHECKED: Allen Liu DATE: FEB/03/2013 DRAWN: Y.Liu PAGE: 4 OF 5 ERP: 1102000679

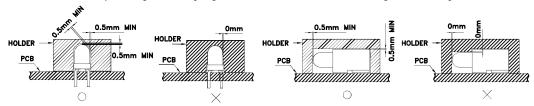
#### **PRECAUTIONS**

 The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

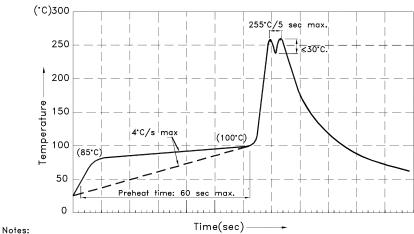


" $\bigcirc$  " Correct mounting method "imes" Incorrect mounting method

2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through—hole LEDs are incompatible with reflow soldering.
- 5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 6. Recommended Wave Soldering Profiles:



1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C

2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above  $85^{\circ}\text{C}$ .

4.Fixtures should not incur stress on the component when mounting and during soldering process.

5.SAC 305 solder alloy is recommended.

6.No more than one wave soldering pass.

All design applications should refer to Kingbright application notes available at <a href="http://www.KingbrightUSA.com/ApplicationNotes">http://www.KingbrightUSA.com/ApplicationNotes</a>

SPEC NO: DSAF2088 REV NO: V.4A DATE: FEB/03/2013 PAGE: 5 OF 5
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Y.Liu ERP: 1102000679